

SBR1U40LP-p

Part Number: **SBR DFN1411-3 Package**
Weight (mg): 2.4634

p = package designator
See Data Sheet

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	7.92	0.1951	1000000	79199
Leadframe	C7025	Cu	7440-50-8	95.90%	41.89	1.0319	959000	401718
		Si	7440-21-3	0.73%			7250	3037
		Ni	7440-02-0	3.20%			32000	13405
		Mg	7439-95-4	0.18%			1750	733
Leadframe Plating	Internal plating	Ni	7440-02-0	100.00%	0.97	0.0239	1000000	9702
	middle plating	Pd	2023568	100.00%	0.09	0.0022	1000000	893
	outer plating	Au	7440-57-5	100.00%	0.02	0.0004	1000000	162
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.77	0.0189	1000000	7672
Encapsulation	EME-G770HCD	Silica fused	60676-86-0	93.50%	44.56	1.0977	935000	416639
		Epoxy resin	-----	3.00%			30000	13368
		Phenol resin	-----	3.00%			30000	13368
		Carbon Black	1333-86-4	0.50%			5000	2228
Die Attach Epoxy	QMI519	Ag	7440-22-4	80.00%	3.79	0.0933	800000	30300
		palladium compound	----	0.15%			1500	57
		2,6-Di-tert-butyl-p-cresol	128-37-0	0.01%			50	2
		Hydroquinone	123-31-9	0.00%			1	0
		Acrylate	----	15.84%			158449	6001
		Bismaleimide resin	----	3.00%			30000	1136
		Polymer of polybutadiene and anlydride	----	1.00%			10000	379
		Total						

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, [Material Composition Declaration for Electronic Products](#).

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

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|--|--|
| Asbestos | Organic tin compounds |
| Antimony Compounds | Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.) |
| Azo compounds | Ozone Depleting Substances - Class II (HCFCs) |
| Cadmium and cadmium compounds | Perfluorooctane Sulphonate (PFOS) or related compounds |
| Certain Shortchain Chlorinated Paraffins | Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE |
| Chlorinated organic compounds | Polychlorinated Biphenyls (PCBs) |
| Dimethyl fumarate | Polychlorinated Naphthalenes (> 3 chlorine atoms) |
| Halogens | Radioactive Substances |
| Hexavalent chromium compounds | Red Phosphorus |
| Lead and lead compounds | Tributyl Tin (TBT) and Triphenyl Tin (TPT) |
| Mercury and mercury compounds | Tributyl Tin Oxide (TBTO) |
| REACH SVHCs and other Substances of Concern: | |
| Anthracene | 5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene) |
| 4,4'- Diaminodiphenylmethane | Bis (2-ethyl(hexyl)phthalate) (DEHP) |
| Dibutyl phthalate | Hexabromocyclododecane (HBCDD) |
| Cyclododecane | Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins) |
| Cobalt dichloride | Bis(tributyltin)oxide |
| Diarsenic pentaoxide | Lead hydrogen arsenate |
| Diarsenic trioxide | Triethyl arsenate |
| Sodium dichromate, dihydrate | Benzyl butyl phthalate |
| Beryllium, Beryllium Alloys and Compounds | Methylene Chloride |
| Hydrazine | Trichloroethene |
| Tetrachloroethylene | Methyl Ethyl Ketone |
| Toluene | Xylenes |
| Toluene Diisocyanate | |